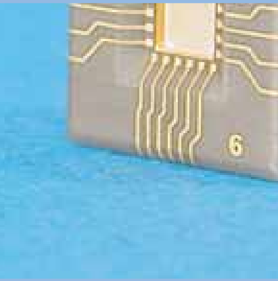
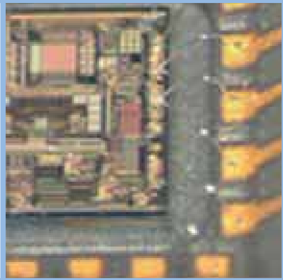
MICROCERTEC
Advanced Ceramics for High-Tech Industries

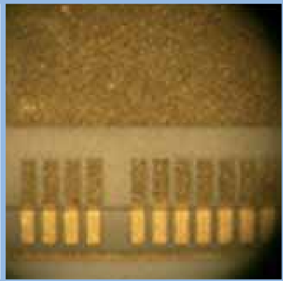
Alumina 3D Chip Carrier

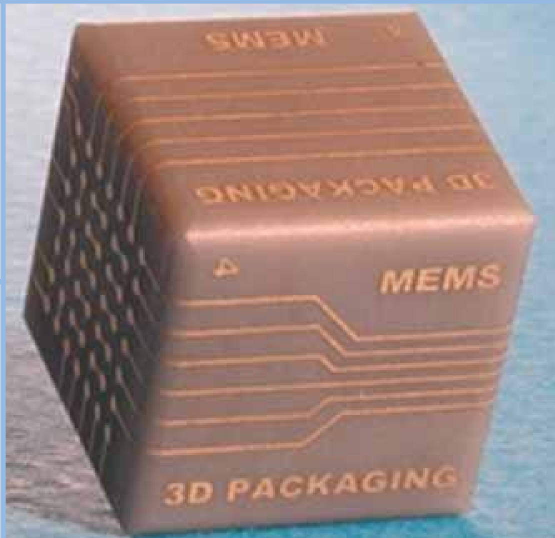
CERAMIC 3D INTERCONNECTION DEVICES




Aluminium nitride 3D interconnection device

Chip assembly on a ceramic CI3D





Products and applications

- Carrier for microelectronics circuits and chips
- Carrier for LEDs
- Carrier for sensors

Materials

- Aluminium oxide (94 to 99,8 %)
- Aluminium nitride
- Quartz

Technology

- 3D components in advanced ceramics
- Thin-film metallising (PACVD) :
  - Thickness up to a few microns
  - Ti / Pt / Au, Cr / Ni / Au
  - Copper, silver, aluminium, indium
- Highly selective laser etching :
  - Electrical tracks 50 µm-wide
  - Insulation 100 µm-wide
  - High accuracy 25 µm

Benefits

- Good electrical insulation
- High thermal dissipation
- Superior dimension stability
- Flexible technology for prototypes and medium-size production runs
- No tool-masks costs

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